AP65211

TSOT26 LIGHT LOAD IMPROVED 2A SYNCH DC-DC BUCK CONVERTER

Description

The AP65211 is a 500kHz switching frequency internal compensated synchronous DC-DC buck converter. It has integrated low $R_{DS(ON)}$ high and low side MOSFETs.

The AP65211 enables continuous load current of up to 2A with efficiency as high as 97%.

The AP65211 implements an automatic custom light load efficiency improvement algorithm.

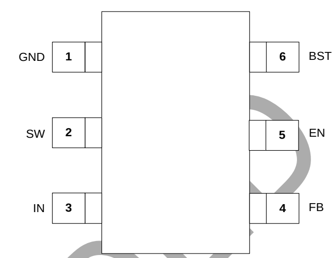
The AP65211 features current mode control operation, which enables fast transient response times and easy loop stabilization.

The AP65211 simplifies board layout and reduces space requirements with its high level of integration and minimal need for external components, making it ideal for distributed power architectures.

The AP65211 is available in a standard Green TSOT26 package and is RoHS compliant.

Pin Assignments

Top View



TSOT26

Features

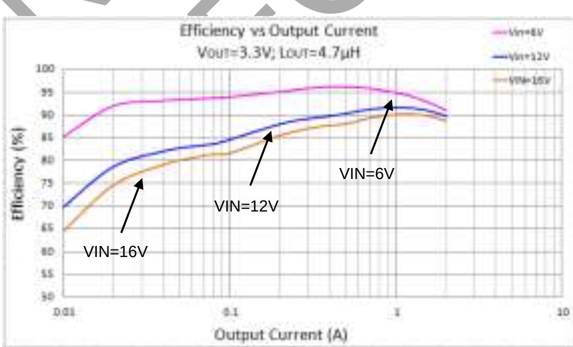
- V_{IN} 6 to 16V
- 2A Continuous Output Current
- Efficiency Up to 97%
- Automated Light Load improvement
- V_{OUT} Adjustable from 0.8V
- 500kHz Switching Frequency
- Internal Soft-Start
- Enable Pin
- Overvoltage Protection & Undervoltage Protection
- Overcurrent Protection (OCP) with Hiccup
- Thermal Protection
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Applications

- Gaming Consoles
- Flat Screen TV Sets and Monitors
- Set-Top-Boxes
- Distributed Power Systems
- Home Audio
- Consumer Electronics
- Network Systems
- FPGA, DSP and ASIC Supplies
- Green Electronics

Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Typical Applications Circuit



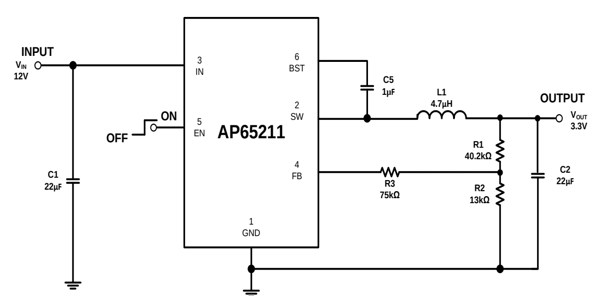
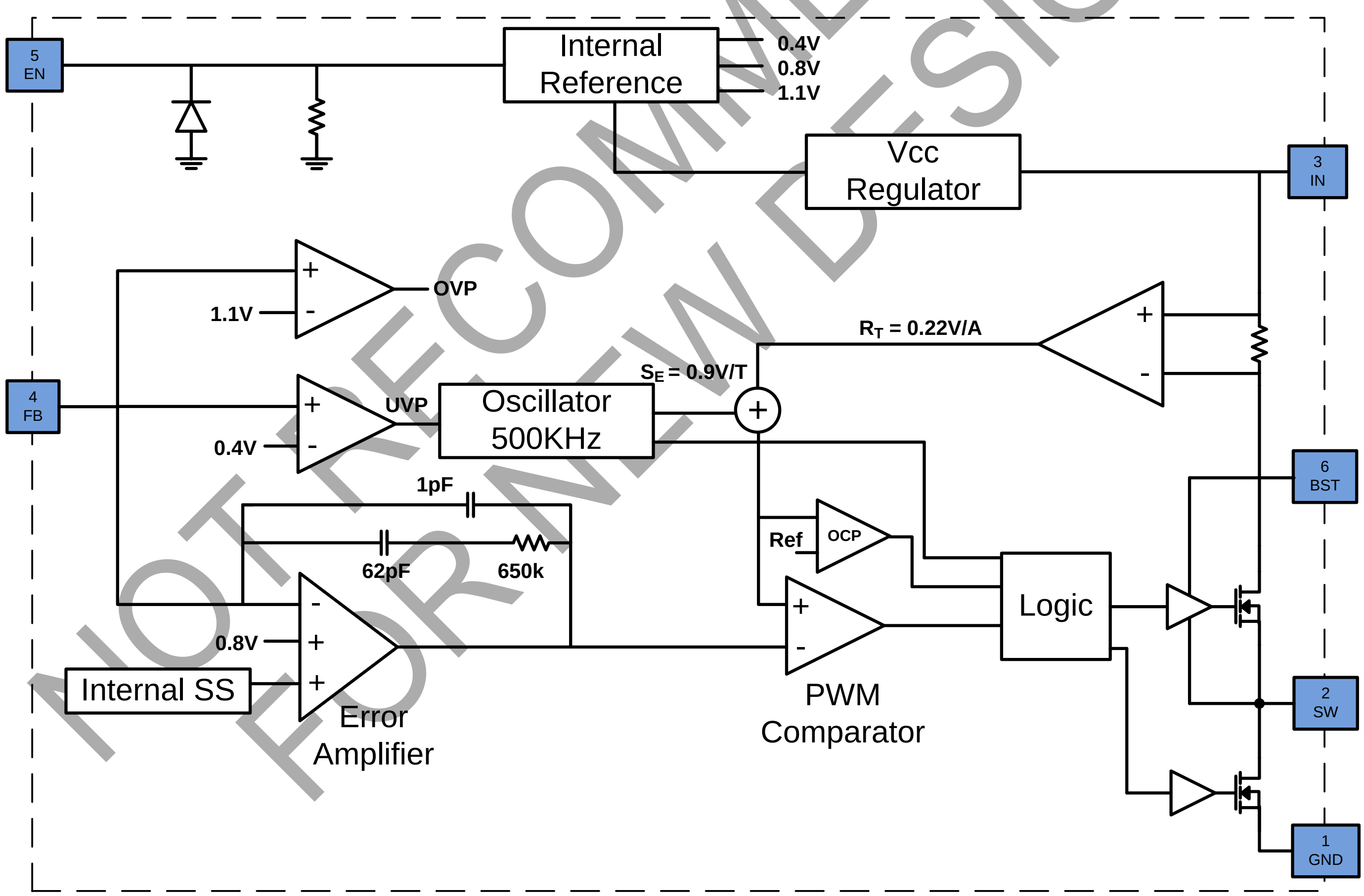


Figure 1 Typical Application Circuit

Pin Descriptions

Pin Name	Pin Number	Function
GND	1	Ground
SW	2	Power Switching Output. SW is the switching node that supplies power to the output. Connect the output LC filter from SW to the output load. Note that a capacitor is required from SW to BS to power the high-side switch.
IN	3	Power Input. IN supplies the power to the IC, as well as the step-down converter switches. Drive IN with a 6V to 16V power source. Bypass IN to GND with a suitably large capacitor to eliminate noise on the input to the IC. See Input Capacitor on Page 10.
FB	4	Feedback Input. FB senses the output voltage and regulates it. Drive FB with a resistive voltage divider connected to it from the output voltage. The feedback threshold is 0.8V. See Setting the Output Voltage on Page 9.
EN	5	Enable Input. EN is a digital input that turns the regulator on or off. Drive EN high to turn on the regulator; low to turn it off. Attach to IN with a 100kΩ pull up resistor for automatic startup.
BST	6	High-Side Gate Drive Boost Input. BS supplies the drive for the high-side N-Channel MOSFET a 0.01µF or greater capacitor from SW to BS to power the high side switch.

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.) (Note 4)

Symbol	Parameter	Rating	Unit
V_{IN}	Supply Voltage	-0.3 to 20	V
V_{SW}	Switch Node Voltage	-1.0 to V_{IN} +0.3	V
V_{BS}	Bootstrap Voltage	V_{SW} -0.3 to V_{SW} +6.0	V
V_{FB}	Feedback Voltage	-0.3V to +6.0	V
V_{EN}	Enable/UVLO Voltage	-0.3V to +6.0	V
T_{ST}	Storage Temperature	-65 to +150	°C
T_J	Junction Temperature	+160	°C
T_L	Lead Temperature	+260	°C
ESD Susceptibility (Note 5)			
HBM	Human Body Model	2	kV
CDM	Charged Device Model	1	kV

Notes: 4. Stresses greater than the 'Absolute Maximum Ratings' specified above may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions exceeding those indicated in this specification is not implied. Device reliability may be affected by exposure to absolute maximum rating conditions for extended periods of time.
5. Semiconductor devices are ESD sensitive and may be damaged by exposure to ESD events. Suitable ESD precautions should be taken when handling and transporting these devices.

Thermal Resistance (Note 6)

Symbol	Parameter	Rating	Unit
θ_{JA}	Junction to Ambient	120	°C/W
θ_{JC}	Junction to Case	30	°C/W

Note: 6. Device mounted on FR-4 substrate, single-layer PC board, 2oz copper, with minimum recommended pad layout.

Recommended Operating Conditions (@T_A = +25°C, unless otherwise specified.) (Note 7)

Symbol	Parameter	Min	Max	Unit
V_{IN}	Supply Voltage	6	16	V
T_A	Operating Ambient Temperature Range	-40	+85	°C

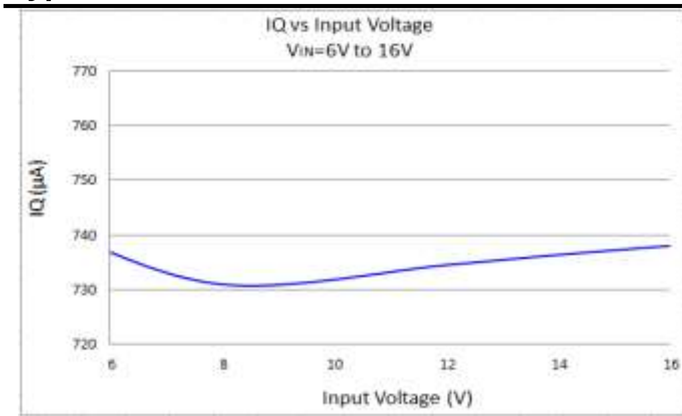
Note: 7. The device function is not guaranteed outside of the recommended operating conditions.

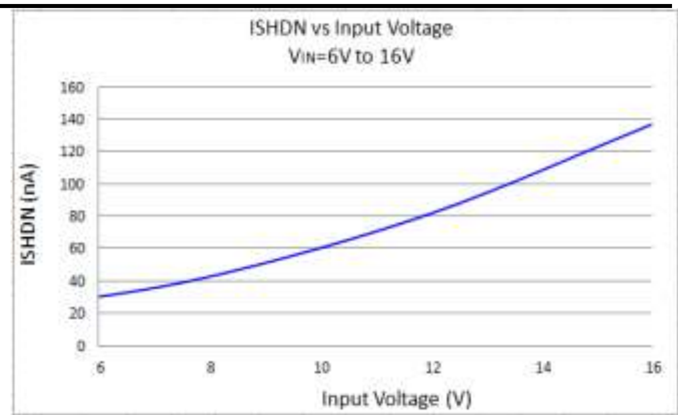
Electrical Characteristics (@T_A = +25°C, V_{IN} = 12V, unless otherwise specified.)

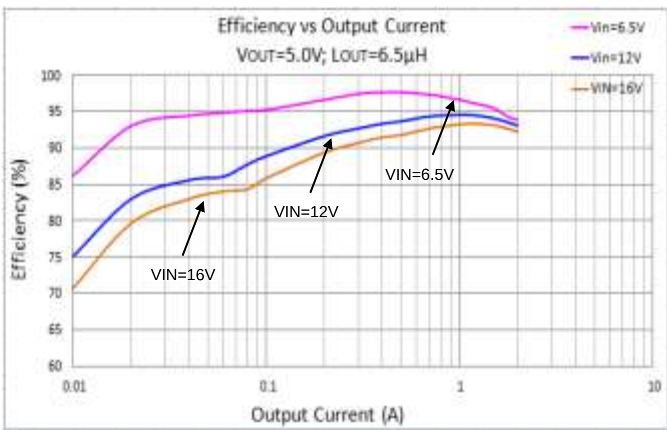
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
I_{SHDN}	Shutdown Supply Current	V_{EN} = 0V	—		1.0	µA
I_Q	Supply Current (Quiescent)	V_{EN} = 2.0V, V_{FB} = 0.85V	—	0.8	—	mA
$R_{DS(ON)1}$	High-Side Switch On-Resistance (Note 8)	—	—	160	—	mΩ
$R_{DS(ON)2}$	Low-Side Switch On-Resistance (Note 8)	—	—	85	—	mΩ
I_{LIMIT_PEAK}	HS Peak Current Limit (Note 8)	Minimum Duty Cycle	3.0	3.5	—	A
I_{SW_LKG}	Switch Leakage Current	V_{EN} = 0V, V_{SW} =12V	—	—	1	µA
F_{SW}	Oscillator Frequency	V_{FB} = 0.75V	400	500	600	kHz
D_{MAX}	Maximum Duty Cycle	V_{FB} = 700mV	88	92	—	%
T_{ON}	Minimum On-Time	—	—	90	—	ns
V_{FB}	Feedback Voltage	T_A = -40°C to +85°C	776	800	824	mV
V_{EN_RISING}	EN Rising Threshold	—	1.4	1.5	1.6	V
$V_{EN\_FALLING}$	EN Falling Threshold	—	1.23	1.32	1.41	V
I_{EN}	EN Input Current	V_{EN} = 2V	—	2.85	—	µA
		V_{EN} = 0V	—	0	—	µA
$INUV_{VTH}$	V_{IN} Undervoltage Threshold Rising	—	3.7	4.05	4.4	V
$INUV_{HYS}$	V_{IN} Undervoltage Threshold Hysteresis	—	—	250	—	mV
T_{SS}	Soft-Start Period	—	—	1	—	ms
T_{SHDN}	Thermal Shutdown (Note 8)	—	—	+160	—	°C
T_{HYS}	Thermal Hysteresis (Note 8)	—	—	+20	—	°C

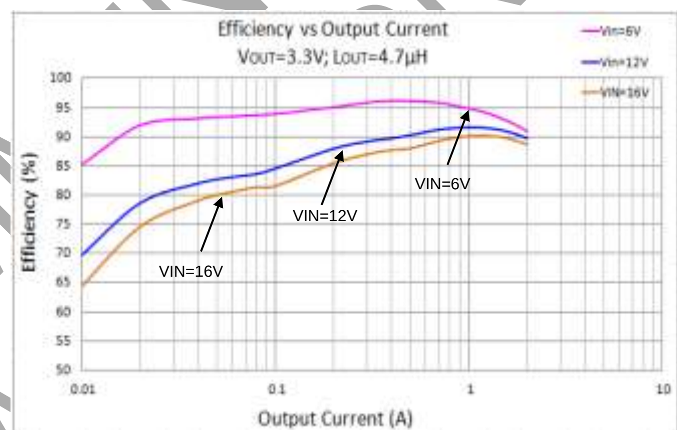
Note: 8. Guaranteed by design.

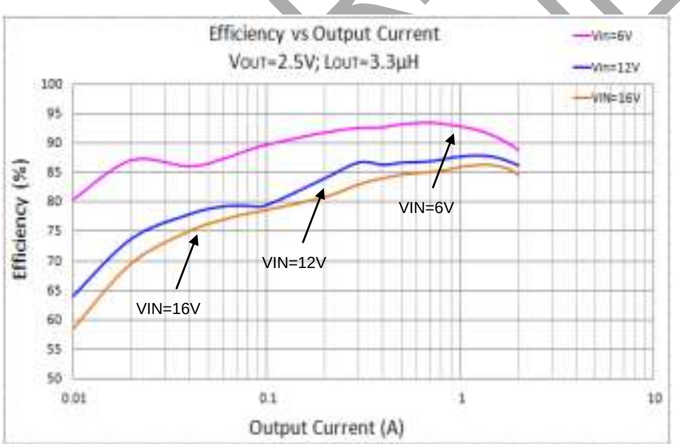
Typical Performance Characteristics (@T_A = +25°C, V_{IN} = 12V, V_{OUT} = 3.3V, L = 4.7µH, unless otherwise specified.)

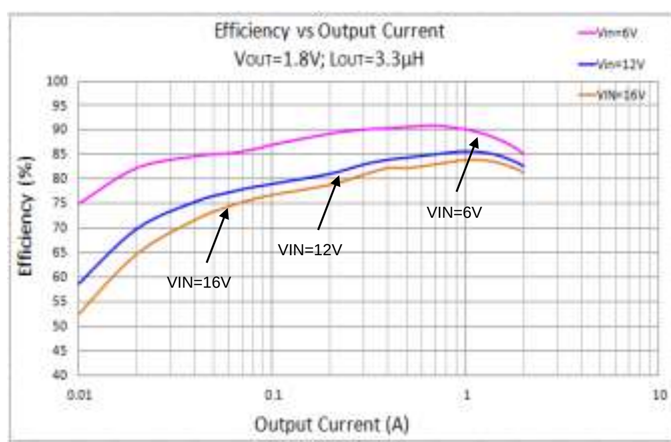






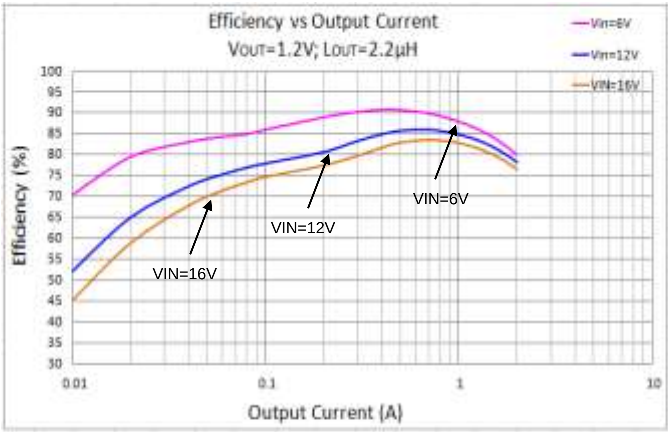


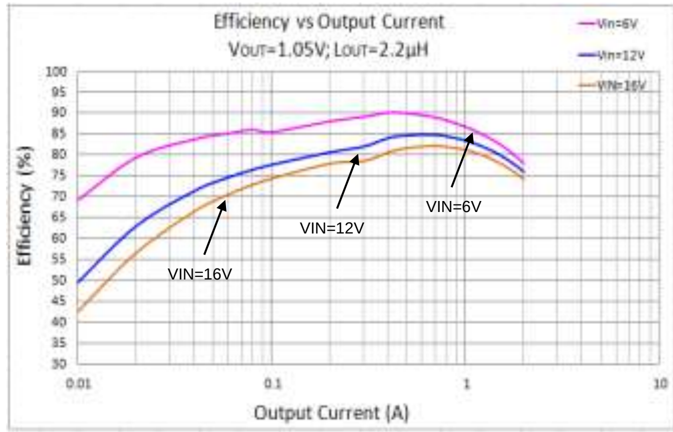


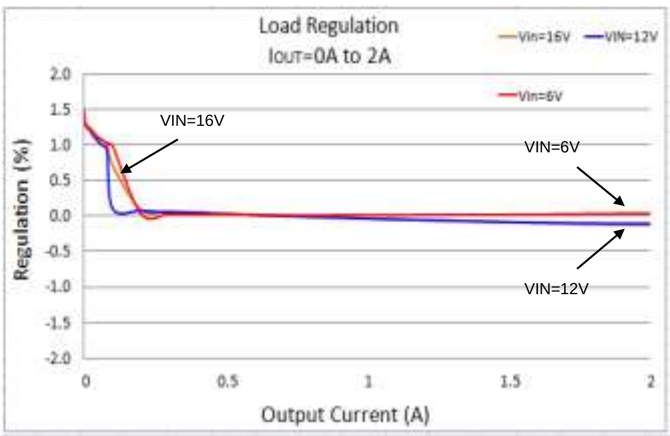


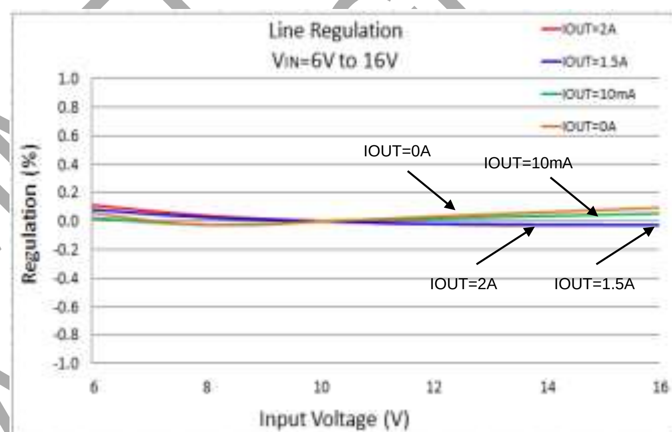
Typical Performance Characteristics (Continued)

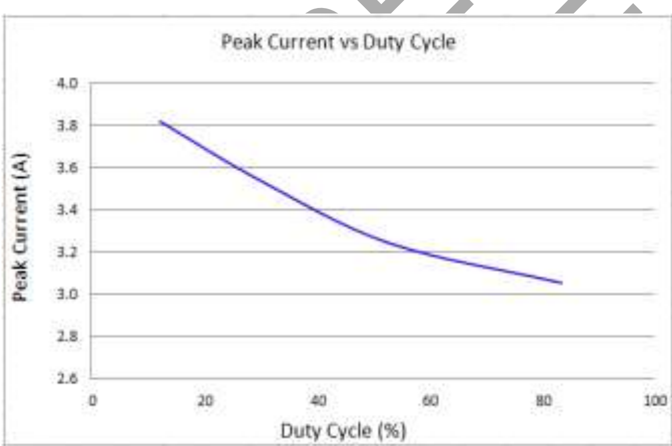
(@T_A = +25°C, V_{IN} = 12V, V_{OUT} = 3.3V, L = 4.7µH, unless otherwise specified.)

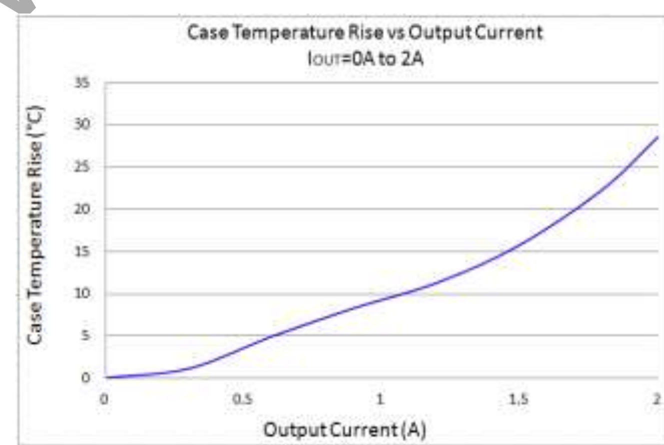








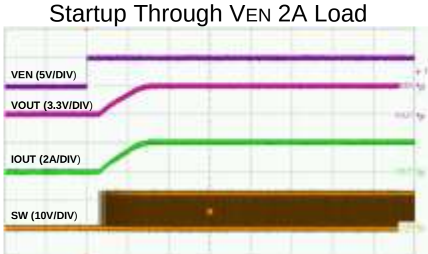




Typical Performance Characteristics (Cont.)

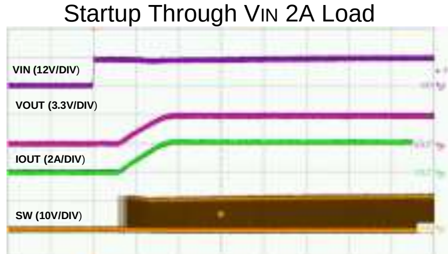
(@T_A = +25°C, V_{IN} = 12V, V_{OUT} = 3.3V, L = 4.7µH, C1 = 22µF, C2 = 22µF, unless otherwise specified.)

Startup Through VEN 2A Load



Time-500µs/div

Startup Through VIN 2A Load

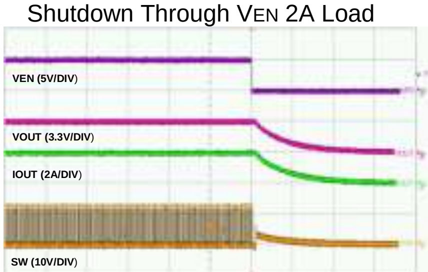


Time-500µs/div

Short Circuit Test

Time-5ms/div

Shutdown Through VEN 2A Load



Time-50µs/div

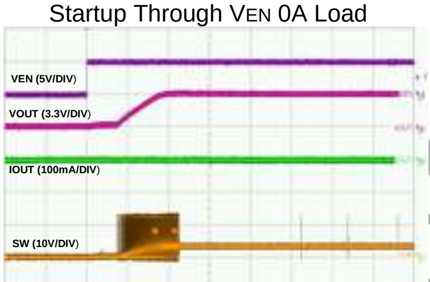
Shutdown Through VIN 2A Load

Time-200µs/div

Short Circuit Recovery

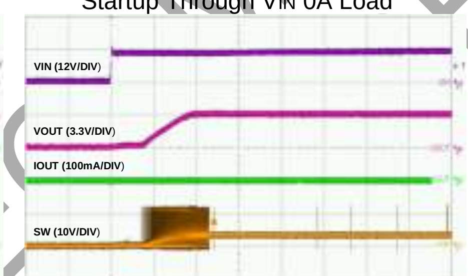
Time-5ms/div

Startup Through VEN 0A Load



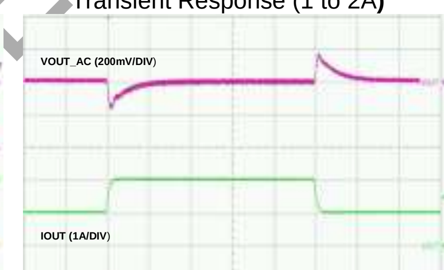
Time-500µs/div

Startup Through VIN 0A Load



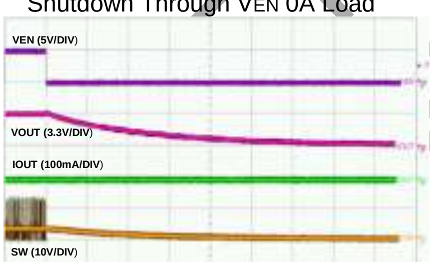
Time-500µs/div

Transient Response (1 to 2A**)**



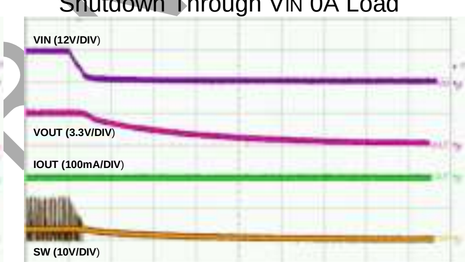
Time-100µs/div

Shutdown Through VEN 0A Load



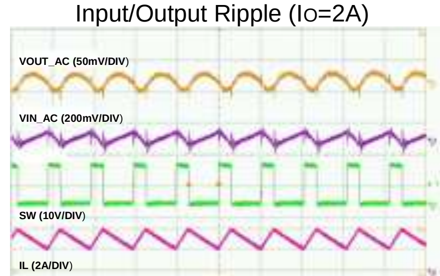
Time-500ms/div

Shutdown Through VIN 0A Load



Time-500ms/div

Input/Output Ripple (IO=2A)



Time-2µs/div

Application Information

Theory of Operation

The AP65211 is a 2A current mode control, synchronous buck regulator with integrated power MOSFETs. Current mode control assures excellent line regulation, load regulation, and a wide loop bandwidth for fast response to load transients. Figure 1 depicts the functional block diagram of AP65211.

The operation of one switching cycle can be explained as follows: The rising edge of the 500kHz oscillator clock signal sets the RS Flip-Flop. Its output turns on HS MOSFET. When the HS MOSFET is on, inductor current starts to increase. The current sense amplifier senses and amplifies the inductor current with a gain of 0.22V/A. Since the current mode control is subject to sub-harmonic oscillations that start at half of the switching frequency, ramp slope compensation of 0.9V/T is utilized. This ramp compensation is summed to the current sense amplifier output and compared to the error amplifier output by the PWM comparator. When the sum of the current sense amplifier output and the slope compensation signal exceeds the EA output voltage, the RS Flip-Flop is reset and HS MOSFET is turned off.

When the HS MOSFET turns off, the synchronous LS MOSFET turns on until the next clock cycle begins. There is a “dead time” between the HS turn off and LS turn on that prevents the switches from “shooting through” across the input supply to ground.

For one whole cycle, if the sum of the current sense amplifier output and the slope compensation signal does not exceed the EA output, then the falling edge of the oscillator clock resets the Flip-Flop, and forces the MOSFET to turn off.

The voltage loop is compensated internally.

Enable

The enable (EN) input allows the user to control turning on or off the regulator. The AP65211 has an internal pull down resistor on the EN pin and when the EN is not actively pulled up the part turns off.

Quiescent Current

Above the ‘EN Rising Threshold’, the internal regulator is turned on and the quiescent current can be measured when V_{FB}>0.8V.

Automated No-Load and Light-Load Operation

The AP65211 operates in light load high efficiency mode during low load current operation. The advantage of this light load efficiency mode is lower power losses at no-load and light-load conditions. The AP65211 automatically detects the inductor’s valley current and enters the light load high efficiency mode when value falls below zero Ampere. Once the inductor’s valley current exceeds zero Ampere, the AP65211 transitions from light load high efficiency mode back to continuous PWM mode.

Application Information (Continued)

Current Limit Protection

In order to reduce the total power dissipation and to protect the application, AP65211 has cycle-by-cycle current limiting implementation. The voltage drop across the internal high-side MOSFET is sensed and compared with the internally set current limit threshold. This voltage drop is sensed at about 30ns after the HS turns on. When the peak inductor current exceeds the set current limit threshold, current limit protection is activated. When the FB voltage pin dropped below 0.4V, the device enters Hiccup mode to periodically restart the part. This protection mode greatly reduces the power dissipated on chip and reduces the thermal stress to help protect the device. AP65211 will exit Hiccup mode when the over current situation is resolved.

Undervoltage Lockout (UVLO)

Undervoltage Lockout is implemented to prevent the IC from insufficient input voltages. The AP65211 has a UVLO comparator that monitors the input voltage and the internal bandgap reference. If the input voltage falls below 4.05V, the AP65211 will latch the undervoltage fault. In this event, the output will be pulled low and power has to be re-cycled to reset the UVLO fault.

Overvoltage Protection

When the AP65211 FB pin exceeds 115% of the nominal regulation voltage of 0.8V, the overvoltage comparator is tripped and internal regulator would stop switching. The V_{OUT} would stay high voltage as tripped point and slowly discharged by output capacitance.

Thermal Shutdown

The AP65211 has on-chip thermal protection that prevents damage to the IC when the die temperature exceeds safe margins. It implements a thermal sensing to monitor the operating junction temperature of the IC. Once the die temperature rises to approximately +160°C, the thermal protection feature gets activated. The internal thermal sense circuitry turns the IC off thus preventing the power switch from damage. A hysteresis in the thermal sense circuit allows the device to cool down to approximately +120°C before the IC is enabled again through soft start. This thermal hysteresis feature prevents undesirable oscillations of the thermal protection circuit.

Setting the Output Voltage

The output voltage can be adjusted from 0.8V using an external resistor divider. Table 1 shows a list of resistor selection for common output voltages. A serial resistor RT is also recommended for improving the system stability, especially for low V_{OUT} (<3.3V). An optional CFF of 10pF to 470pF used to boost the phase margin. Resistor R1 is selected based on a design tradeoff between efficiency and output voltage accuracy. For high values of R1 there is less current consumption in the feedback network. R1 can be determined by the following equation:

$$R_1 = R_2 \cdot \left(\frac{V_{OUT}}{0.8} - 1 \right)$$

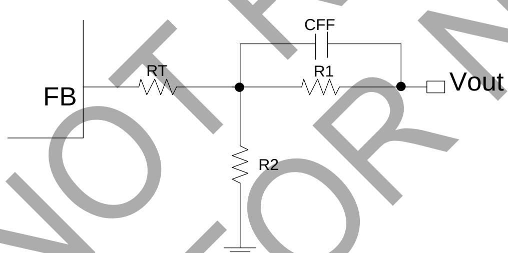


Figure 2 Feedback Divider Network

V_{OUT} (V)	R1 (kΩ)	R2 (kΩ)	RT (kΩ)	L1 (µH)
1.05	10	32.4	300	1.5
1.2	15	30.1	249	1.5
1.8	40.2	32.4	120	2.2
2.5	40.2	19.1	100	2.2
3.3	40.2	13	75	4.7
5	40.2	7.68	75	6.5

Table 1 Recommended Component Selection

Application Information (Cont.)

Inductor

Calculating the inductor value is a critical factor in designing a buck converter. For most designs, the following equation can be used to calculate the inductor value;

$$L = \frac{V_{OUT} \cdot (V_{IN} - V_{OUT})}{V_{IN} \cdot \Delta I_L \cdot f_{SW}}$$

Where ΔI_L is the inductor ripple current and f_{SW} is the buck converter switching frequency.

Choose the inductor ripple current to be 30% to 40% of the maximum load current. The maximum inductor peak current is calculated from:

$$I_{L(MAX)} = I_{LOAD} + \frac{\Delta I_L}{2}$$

Peak current determines the required saturation current rating, which influences the size of the inductor. Saturating the inductor decreases the converter efficiency while increasing the temperatures of the inductor and the internal MOSFETs. Hence choosing an inductor with appropriate saturation current rating is important.

A 1µH to 10µH inductor with a DC current rating of at least 25% higher than the maximum load current is recommended for most applications. For highest efficiency, the inductor's DC resistance should be less than 20mΩ. Use a larger inductance for improved efficiency under light load conditions.

Input Capacitor

The input capacitor reduces the surge current drawn from the input supply and the switching noise from the device. The input capacitor has to sustain the ripple current produced during the on time on the upper MOSFET. It must hence have a low ESR to minimize the losses.

The RMS current rating of the input capacitor is a critical parameter that must be higher than the RMS input current. As a rule of thumb, select an input capacitor which has RMs rating that is greater than half of the maximum load current.

Due to large di/dt through the input capacitors, electrolytic or ceramics should be used. If a tantalum must be used, it must be surge protected. Otherwise, capacitor failure could occur. For most applications, a 10/22µF ceramic capacitor is sufficient and 0.1µF serial capacitor is also recommended for improving the stability.

Output Capacitor

The output capacitor keeps the output voltage ripple small, ensures feedback loop stability and reduces the overshoot of the output voltage. The output capacitor is a basic component for the fast response of the power supply. In fact, during load transient, for the first few microseconds it supplies the current to the load. The converter recognizes the load transient and sets the duty cycle to maximum, but the current slope is limited by the inductor value.

Maximum capacitance required can be calculated from the following equation:
ESR of the output capacitor dominates the output voltage ripple. The amount of ripple can be calculated from the equation below:

$$Vout_{capacitor} = \Delta I_{inductor} * ESR$$

An output capacitor with ample capacitance and low ESR is the best option. For most applications, a 22µF ceramic capacitor will be sufficient.

$$C_o = \frac{L(I_{out} + \frac{\Delta I_{inductor}}{2})^2}{(\Delta V + V_{out})^2 - V_{out}^2}$$

Where ΔV is the maximum output voltage overshoot.

Application Information (Cont.)

PC Board Layout

This is a high switching frequency converter. Hence, attention must be paid to the switching currents interference in the layout. Switching current from one power device to another can generate voltage transients across the impedances of the interconnecting bond wires and circuit traces. These interconnecting impedances should be minimized by using wide, short printed circuit traces.

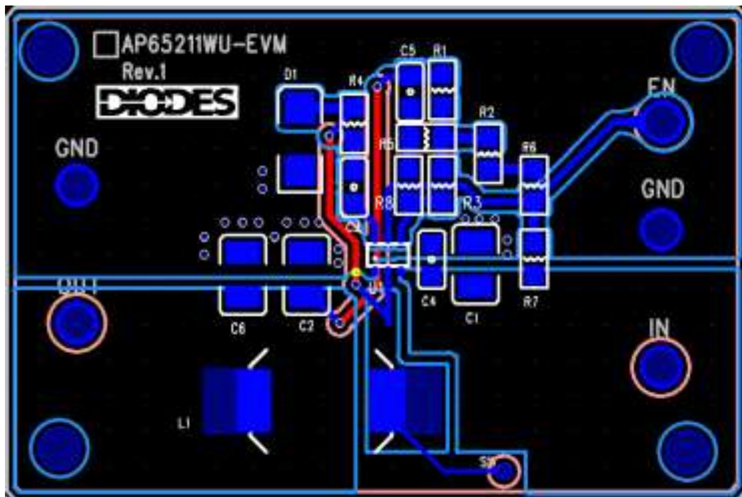


Figure 3 PC Board Layout

Ordering Information (Note 9)

AP65211WU - 7

Package: WU : TSOT26

Packing: 7 : Tape & Reel

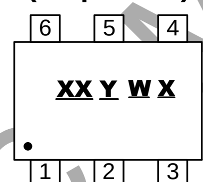
Part Number	Package Code	Package	Identification Code	Tape and Reel	
				Quantity	Part Number Suffix
AP65211WU-7	WU	TSOT26	S8	3,000	-7

Note: 9. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

TSOT26

(Top View)



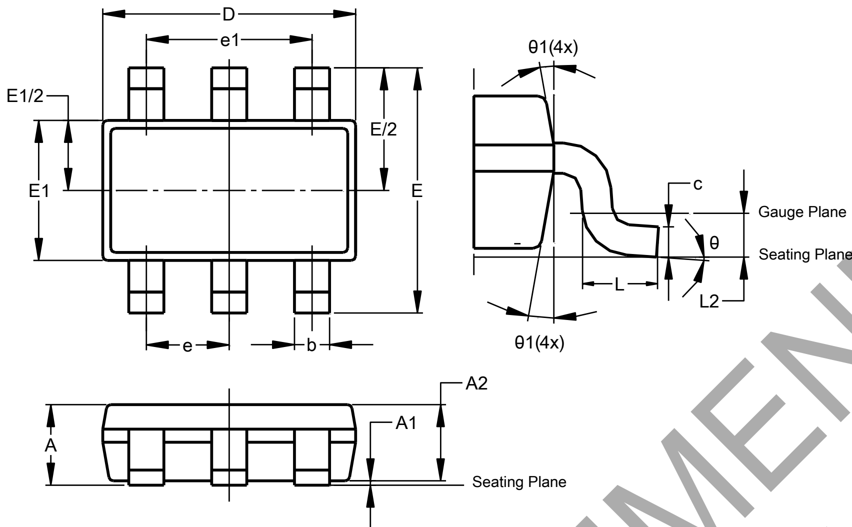
XX : Identification Code
Y : Year 0~9
W : Week : A~Z : 1~26 week; a~z : 27~52 week; z represents 52 and 53 week
X : Internal Code

Part Number	Package	Identification Code
AP65211WU-7	TSOT26	S8

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT26

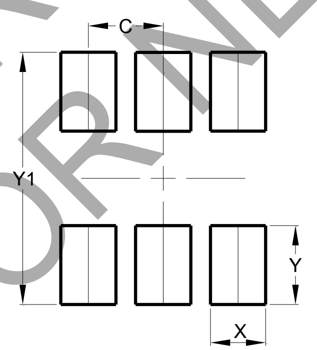


TSOT26			
Dim	**Min**	**Max**	**Typ**
A	–	1.00	–
A1	0.010	0.100	–
A2	0.840	0.900	–
D	2.800	3.000	2.900
E	2.800 BSC		
E1	1.500	1.700	1.600
b	0.300	0.450	–
c	0.120	0.200	–
e	0.950 BSC		
e1	1.900 BSC		
L	0.30	0.50	–
L2	0.250 BSC		
θ	0°	8°	4°
θ1	4°	12°	–
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

TSOT26



Dimensions	Value (in mm)
C	0.950
X	0.700
Y	1.000
Y1	3.199